



PATENT
Atty. Dkt. No. AMAT/1931/CALB/COPPER/PJS

2814 (PAF)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Chen et al.

Serial No.: 08/856,116

Confirmation No.: 2582

Filed: May 14, 1997

For: RELIABILITY BARRIER
INTEGRATION FOR CU
APPLICATION

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Group Art Unit: 2814

Examiner: G. Peralta

CERTIFICATE OF MAILING

37 CFR 1.8

I hereby certify that this correspondence is being deposited on
December 20, 2001, with the United States Postal Service as
First Class Mail in an envelope addressed to: Assistant
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12/20/01
Date

Kent R. Mahr
Signature

RESPONSE TO FINAL OFFICE ACTION DATED OCTOBER 10, 2001

In response to the Final Office Action dated October 10, 2001, having a shortened statutory period for response set to expire on January 10, 2002, please enter the following amendments and reconsider the claims pending in the application for reasons discussed below.

THE PENDING CLAIMS:

15. A method of filling a feature in a dielectric layer, comprising:
 - a) depositing a first barrier layer over a blanket dielectric layer;
 - b) forming a feature through the first barrier layer and the dielectric layer to expose an underlayer;
 - c) depositing a second barrier layer on a bottom and sidewalls in the feature;
 - d) removing the second barrier layer formed at the bottom of the feature;and